2SC5829

Silicon NPN epitaxial planar type

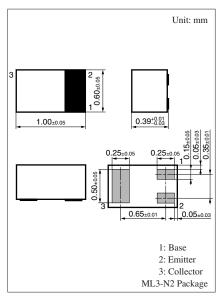
For high speed switching

■ Features

- Allowing the small current and low voltage operation
- High transition frequency f_T
- Suitable for high-density mounting and downsizing of the equipment for Ultraminiature leadless package
 0.6 mm × 1.0 mm (height 0.39 mm)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	10	V	
Collector-emitter voltage (Base open)	V _{CEO}	7	V	
Emitter-base voltage (Collector open)	V_{EBO}	2	V	
Collector current	I_C	10	mA	
Collector power dissipation	P _C	50	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Marking Symbol: X

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 10 \text{ V}, I_{E} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 1.5 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h_{FE}	$V_{CE} = 1 \text{ V}, I_C = 1 \text{ mA}$	100		200	_
Transition frequency	f_T	$V_{CE} = 1 \text{ V}, I_{C} = 1 \text{ mA}, f = 0.8 \text{ GHz}$		4		GHz
Collector output capacitance	C _{ob}	$V_{CB} = 1 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		0.4		pF
(Common base, input open circuited)						
Forward transfer gain	S _{21e} 2	$V_{CE} = 1 \text{ V}, I_{C} = 1 \text{ mA}, f = 0.8 \text{ GHz}$		6		dB
Maximum unilateral power gain	G_{UM}	$V_{CE} = 1 \text{ V}, I_{C} = 1 \text{ mA}, f = 0.8 \text{ GHz}$		15		dB
Noise figure	NF	$V_{CE} = 1 \text{ V}, I_{C} = 1 \text{ mA}, f = 0.8 \text{ GHz}$		3.5		dB

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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